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(54) MEMBER FOR SEMICONDUCTOR MANUFACTURING APPARATUS, PLUG, AND METHOD OF MANUFACTURING PLUG

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(57)ABSTRACT

A member for semiconductor manufacturing apparatus includes a ceramic plate that has an upper surface that includes a wafer placement portion, and a plug that is installed in a plug installation hole extending through the ceramic plate in an up-down direction and that allows gas to pass therethrough, wherein the plug has a gas flow path that includes a plurality of linear flow paths that is combined such that the plurality of linear flow paths intersects with each other in a plug body, and wherein the gas flow path includes a plurality of opening portions in an upper surface and a lower surface of the plug body.

